

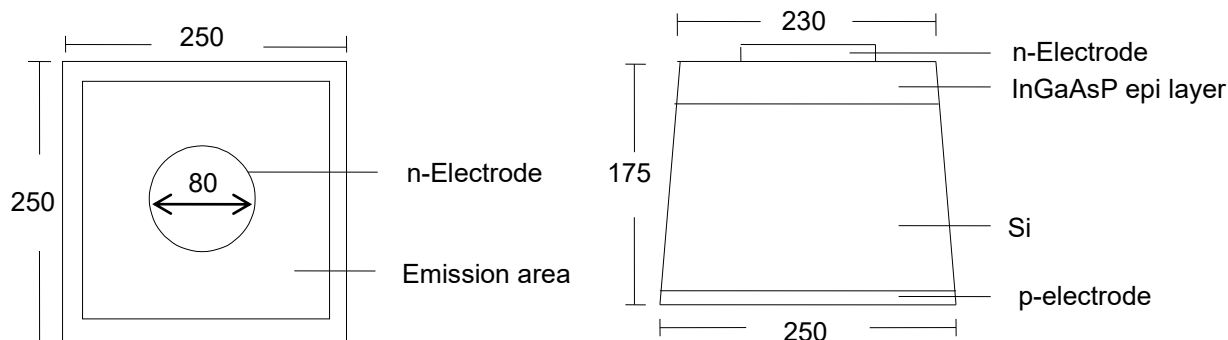
■ Features :

- Suitable for new creative products

■ Typical Applications :

- Sensing
- Moisture detection

■ Outline Dimensions : (Unit: μm)



■ Physical Structure :

LED Chip dimension	Chip size	250 x 250 $\pm$ 25 μm
	Thickness	175 $\pm$ 25 μm
	Emission area	230 μm
	Bonding pad	80 $\pm$ 10 μm
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold
Surface condition	Frosted	

*OMRRU

■ Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	V_F	$I_F = 30 \text{ mA}$	0.8	-	1.1	V
Reverse current	I_R	$V_R = 5 \text{ V}$	-	-	1.0	μA
Peak wavelength	λ_P	$I_F = 30 \text{ mA}$	1420	-	1480	nm
Radiant power	P_o	$I_F = 30 \text{ mA}$	2.2	2.5	-	mW

*LED chip is mounted on TO-18 gold header without resin coated

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

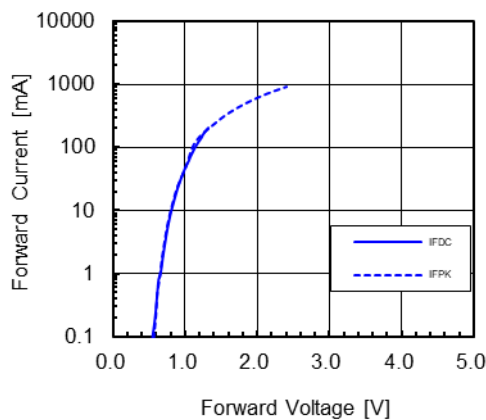


Fig 2. Relative Radiant Power vs. Wavelength

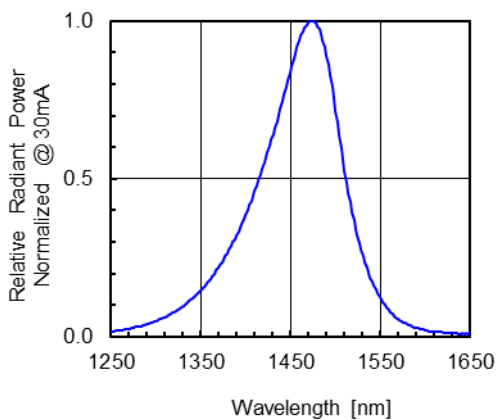


Fig 3. Relative Radiant Power vs. Forward DC Current

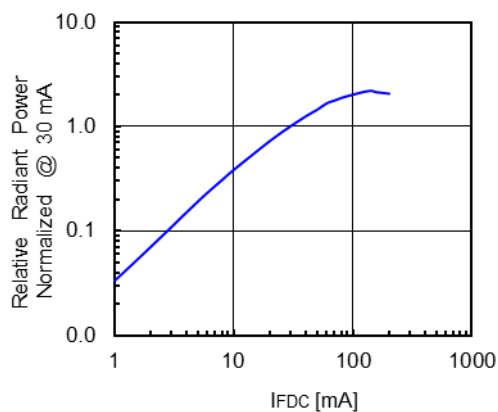


Fig 4. Relative Radiant Power vs. Forward Peak Current

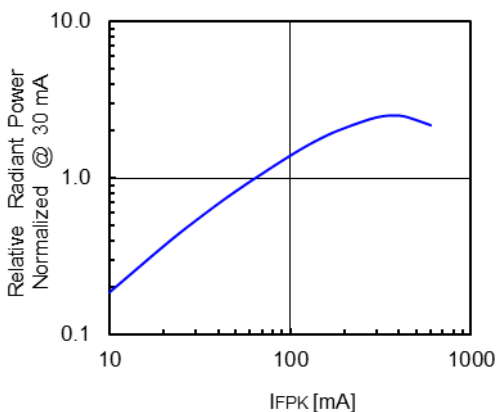


Fig 5. Forward DC Voltage vs. Temperature

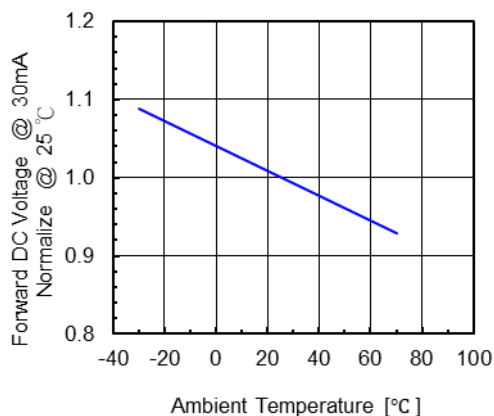


Fig 6. Relative Radiant Power vs. Temperature

